

# ThermaTEC™ Series HT6-12-F2-4040

## Thermoelectric Modules



*Note: This product has reached end of production and is available on a limited basis only. This product series has been replaced with the improved HiTemp ET Series product offering. Consider using ET6-12-F2-4040 HiTemp ET Series module as a replacement.*

The ThermaTEC™ Series of thermoelectric modules (TEMs) are designed to operate under cycling conditions or high temperature applications.

This product line is available in multiple configurations and is ideal for applications that require both heating and cooling mode (reverse polarity) or power generation. Assembled with proprietary solder construction, Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the ThermaTEC™ Series is designed for higher current and larger heat-pumping applications.

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### FEATURES

- Thermal cycling durability
- Power cycling reliability
- Precise temperature control
- Strong lead attachment
- RoHS compliant
- Continuous operation at high temperatures

### APPLICATIONS

- Analytical instrumentation
- PCR cyclers
- Thermal test sockets
- Electronic enclosure cooling
- Chillers (liquid cooling)
- Power generation

### PERFORMANCE SPECIFICATIONS

TECHNICAL		
Hot Side Temperature (°C)	25°C	50°C
Qmax (Watts)	51.6	56.7
Delta Tmax (°C)	63	75
I <sub>max</sub> (Amps)	6.0	6.0
V <sub>max</sub> (Volts)	14.5	16.4
Module Resistance (Ohms)	2.12	2.38

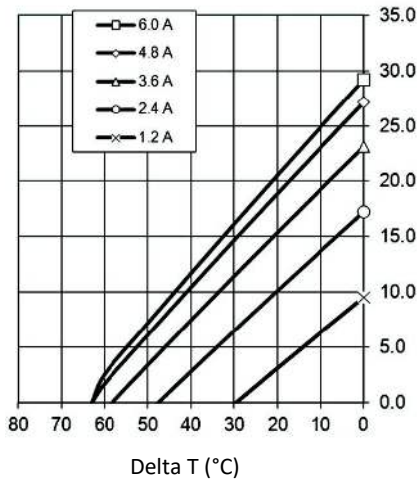
SUFFIX	THICKNESS (PRIOR TO TINNING)	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
11	0.143" +/- 0.005"	0.002"/0.0035"	Lapped	Lapped	6.0
TA	0.143" +/- 0.001"	0.001" / 0.001"	Lapped	Lapped	6.0"
TB	0.143" +/- 0.0005"	0.0005" / 0.0005"	Lapped	Lapped	6.0"

### SEALING OPTIONS

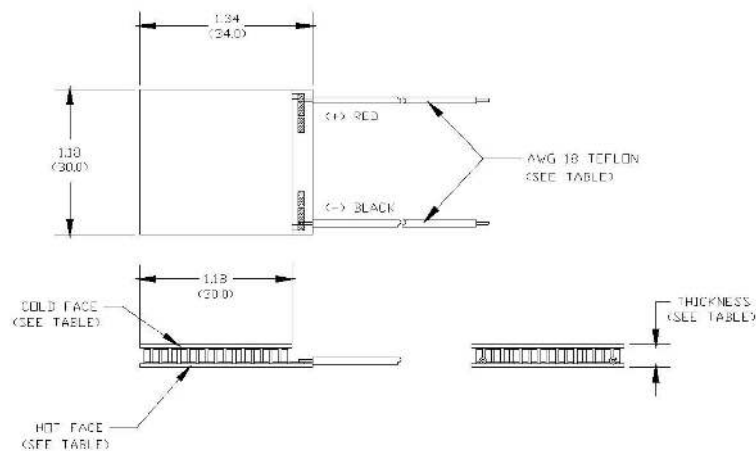
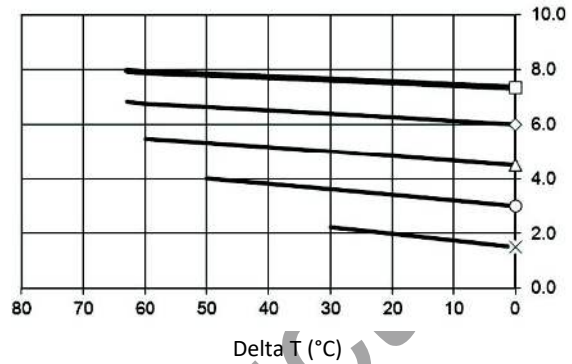
SUFFIX	SEALANT	COLOR	TEMP RANGE	DESCRIPTION
R	RTV	White	-60 to 204 °C	Non-corrosive, silicone adhesive sealant
E	Epoxy	Black	-55 to 150 °C	Low density syntactic foam epoxy encapsulant

Performance Curves at Th =25°C

THERMO



ELECTRIC



Ceramic Material: Alumina (Al<sub>2</sub>O<sub>3</sub>)  
 Solder Construction: 271°C, Proprietary

OPERATING TIPS

- Max Operating Temperature: 175°C
- Do not exceed I<sub>max</sub> or V<sub>max</sub> when operating module
- Reference assembly guidelines for recommended installation

THR-DS-HT6-12-F2-4040

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